

# 2SK1301

## Silicon N Channel MOS FET

REJ03G0920-0200

(Previous: ADE-208-1259)

Rev.2.00 Sep 07, 2005

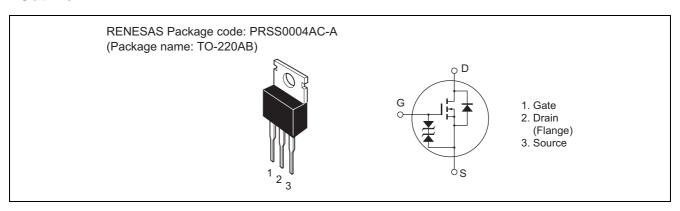
## **Application**

High speed power switching

### **Features**

- Low on-resistance
- High speed switching
- Low drive current
- 4 V gate drive device
  - Can be driven from 5 V source
- Suitable for motor drive, DC-DC converter, power switch and solenoid drive

#### **Outline**



## **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Ratings	Unit	
Drain to source voltage	$V_{DSS}$	100	V	
Gate to source voltage	$V_{GSS}$	±20	V	
Drain current	I <sub>D</sub>	15	Α	
Drain peak current	I <sub>D(pulse)</sub> *1	60	А	
Body to drain diode reverse drain current	I <sub>DR</sub>	15	Α	
Channel dissipation	Pch <sup>*2</sup>	50	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1%

2. Value at  $T_C = 25^{\circ}C$ 

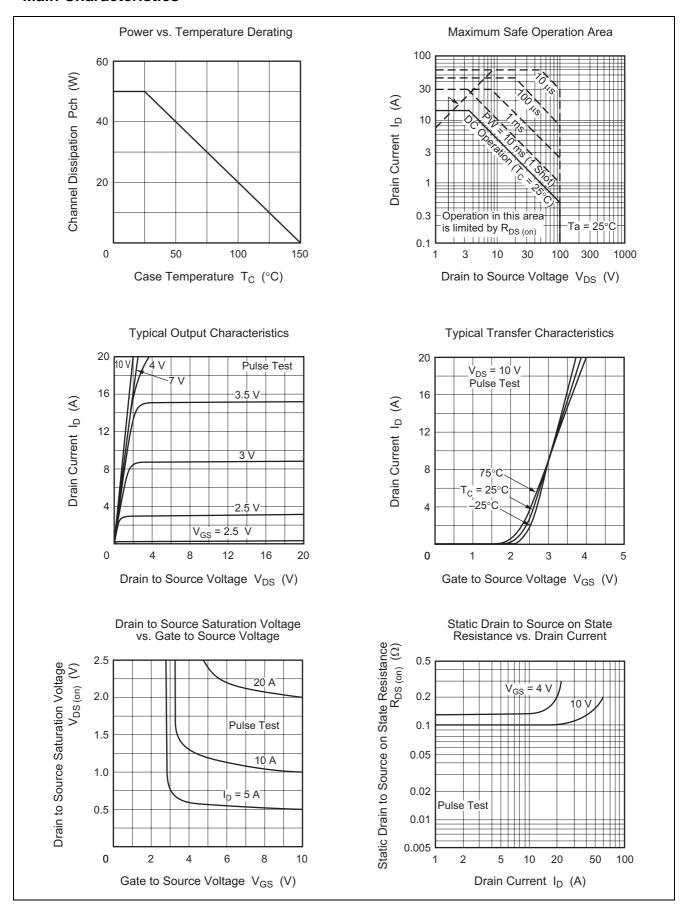
### **Electrical Characteristics**

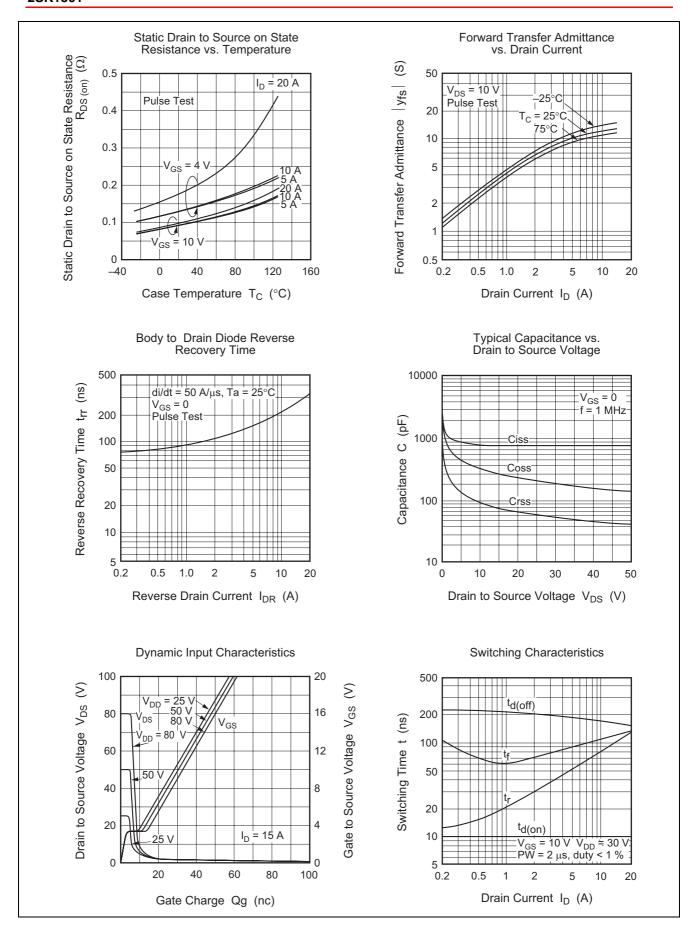
 $(Ta = 25^{\circ}C)$ 

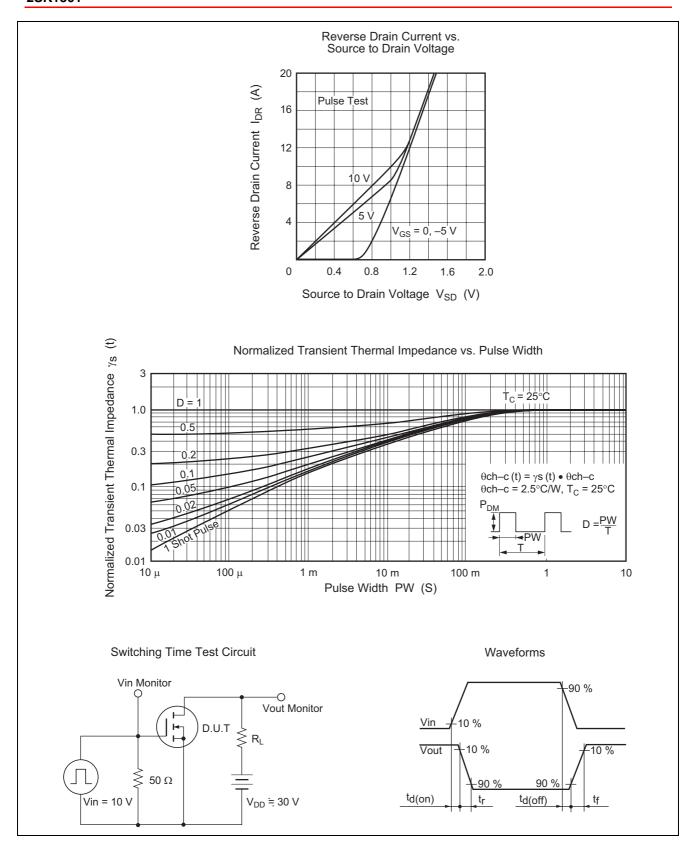
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	100	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V <sub>(BR)GSS</sub>	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	$I_{GSS}$	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	1	_	250	μΑ	$V_{DS} = 80 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	_	2.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state	R <sub>DS(on)</sub>	_	0.10	0.13	Ω	$I_D = 8 \text{ A}, V_{GS} = 10 \text{ V}^{*3}$
resistance		_	0.13	0.18	Ω	$I_D = 8 A, V_{GS} = 4 V^{*3}$
Forward transfer admittance	y <sub>fs</sub>	7	11	_	S	$I_D = 8 \text{ A}, V_{DS} = 10 \text{ V}^{*3}$
Input capacitance	Ciss	_	860	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	340	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	100	_	pF	]
Turn-on delay time	t <sub>d(on)</sub>	_	10	_	ns	$I_D = 8 A, V_{GS} = 10 V,$
Rise time	t <sub>r</sub>	_	70	_	ns	$R_L = 3.75 \Omega$
Turn-off delay time	t <sub>d(off)</sub>	_	180	_	ns	]
Fall time	t <sub>f</sub>	_	100	_	ns	]
Body to drain diode forward voltage	$V_{DF}$	_	1.3	_	V	$I_F = 15 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t <sub>rr</sub>		250	_	ns	$I_F = 15 \text{ A}, V_{GS} = 0,$ $di_F/dt = 50 \text{ A}/\mu\text{s}$

Note: 3. Pulse test

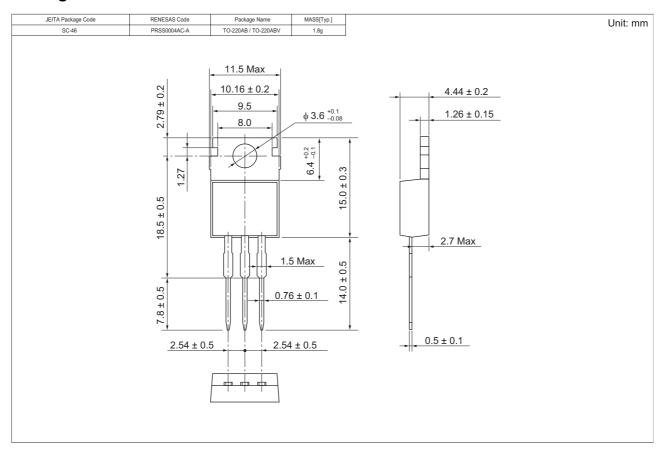
### **Main Characteristics**







## **Package Dimensions**



## **Ordering Information**

Part Name	Quantity	Shipping Container
2SK1301-E	500 pcs	Box (Sack)

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